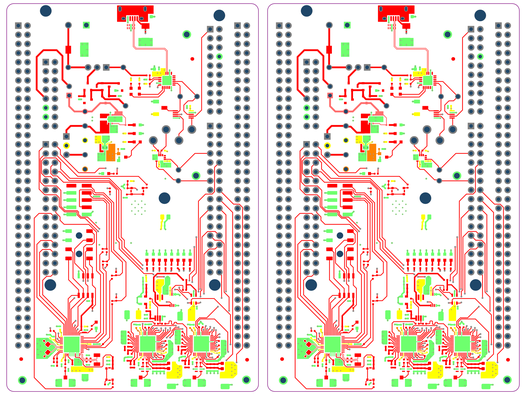
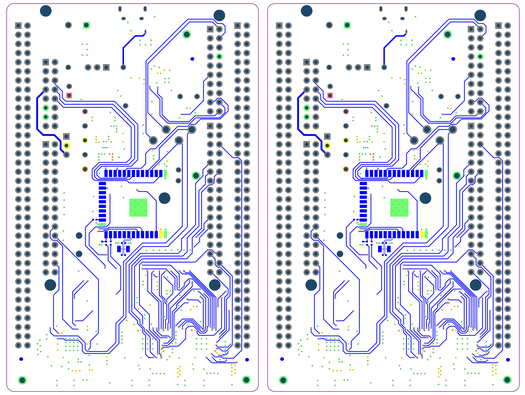


LAYER 1: TOP

BOARD OUTLINE

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.39mil	3.5	
1	Top	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
3	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
4	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.39mil	3.5	
	Bottom Overlay				

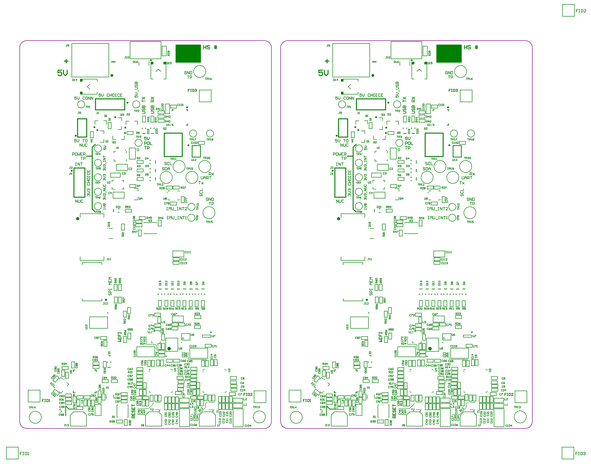


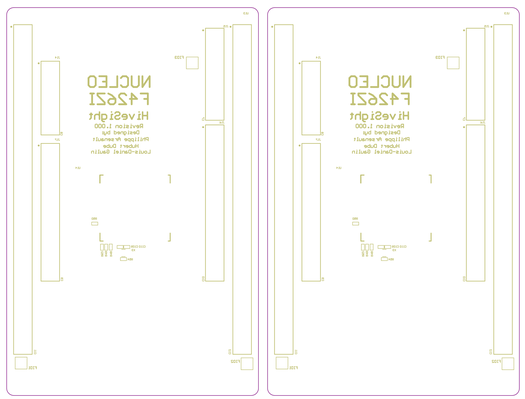
LAYER 4: BOTTOM

BOARD OUTLINE

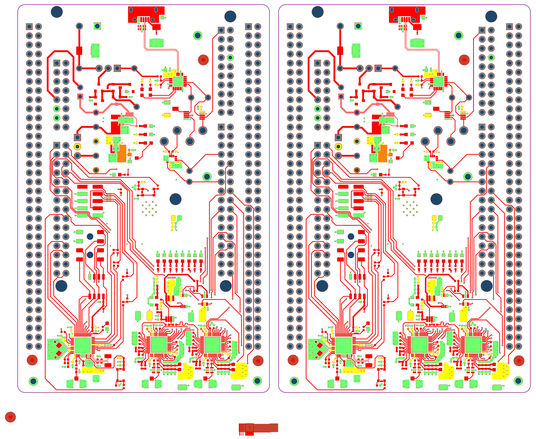
TOP SILKSCREEN

BOARD OUTLINE


5V
5V CHOICE
POWER
EXT
INT
NC
HS
GND
VIN
SCL
SDA
GND
3V3
INT1
INT2
GND
VDD
SCL
SDA
GND
INT1
INT2
GND
VDD
SCL
SDA
GND
INT1
INT2
GND
VDD
SCL
SDA
GND



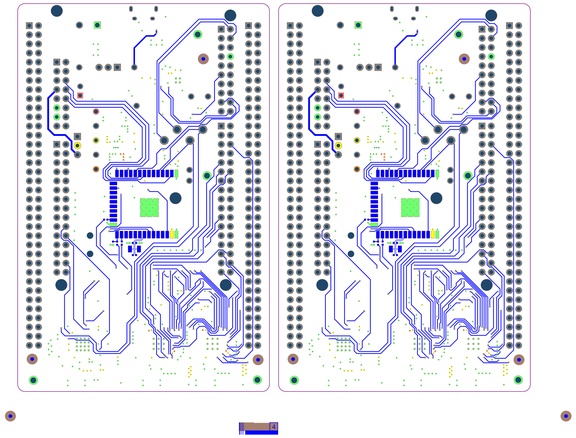
BOTTOM_SILKSCREEN
BOARD_OUTLINE



TOP SOLDERMASK
LAYER 1: TOP

BOARD OUTLINE

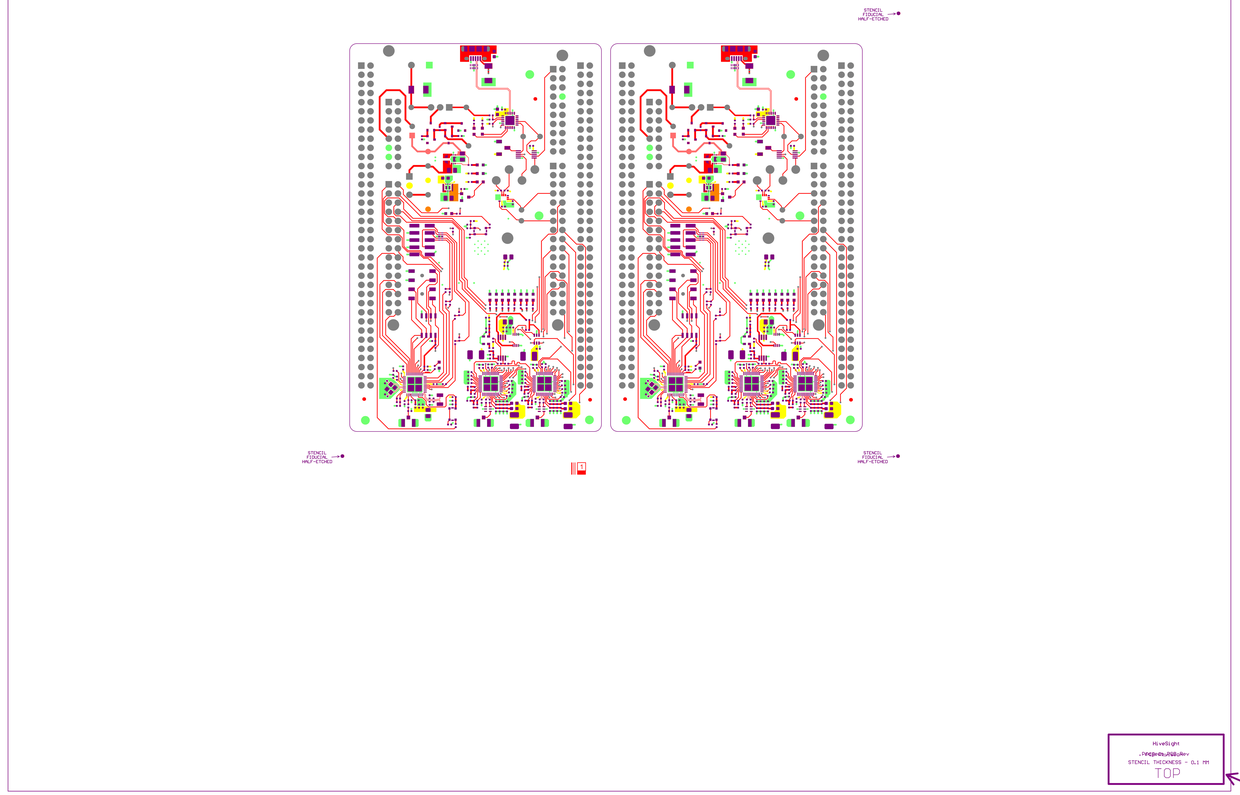
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.39mil	3.5	
1	Top	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
3	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
4	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.39mil	3.5	
	Bottom Overlay				



LAYER 4: BOTTOM
BOTTOM SOLDERMASK

BOARD OUTLINE

FRAME SIZE - 420 x 520 mm



VALID AREA - 240 x 340 mm

Half-Etched
Lasered Text
DO NOT REMOVE

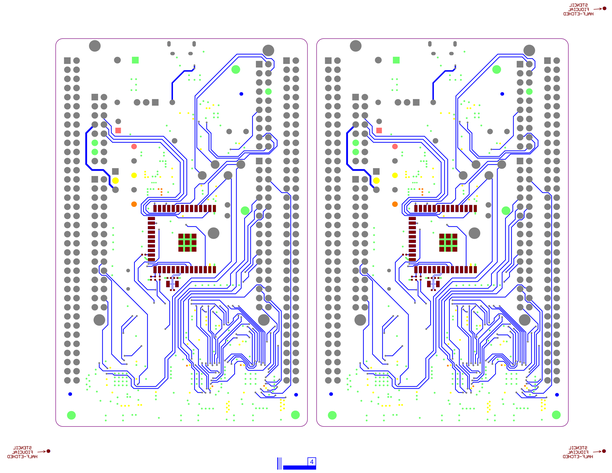
STENCIL THICKNESS - 0.1 MM

LAYER 1: TOP

BOARD OUTLINE

TOP PASTEMASK

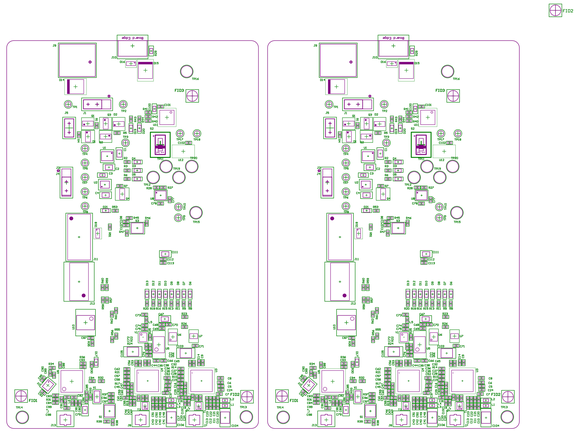
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.39mil	3.5	
1	Top	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
3	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
4	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.39mil	3.5	
	Bottom Overlay				



LAYER 4: BOTTOM

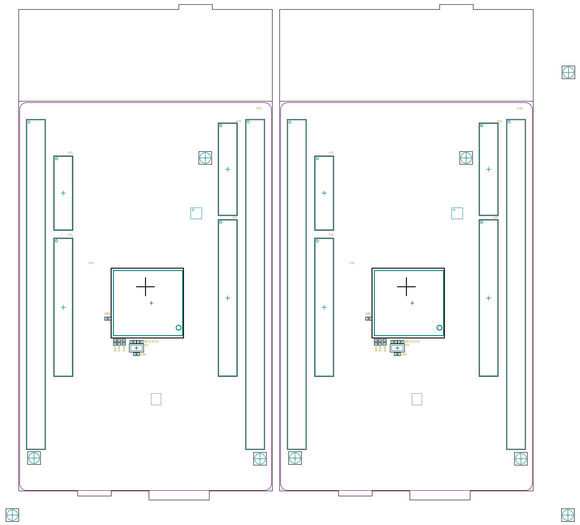
BOARD OUTLINE

BOTTOM PASTEMASK



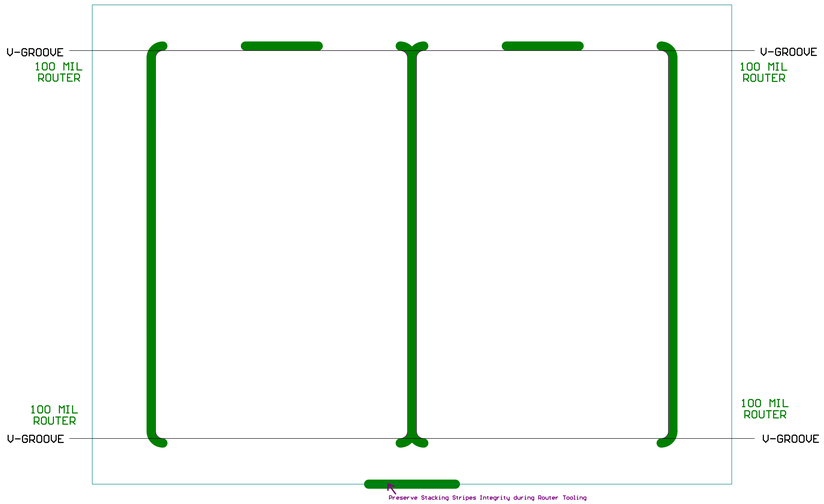
BOARD OUTLINE

TOP ASSEMBLY
TOP DESIGNATORS
TOP COURTYARD



BOARD OUTLINE

BOTTOM ASSEMBLY
BOTTOM COURTYARD
BOTTOM DESIGNATORS



BOARD OUTLINE
PANEL OUTLINE
ROUTE TOOL PATH
PANEL V-GROOVE

MANUFACTURING NOTES